



General Description

The 954206B is a CK410M Compliant clock synthesizer. 954206B provides a single-chip solution for mobile systems built with Intel P4-M processors and Intel mobile chipsets. 954206B is driven with a 14.318MHz crystal and generates CPU outputs up to 400MHz. It provides the tight ppm accuracy required by Serial ATA and PCI Express.

Recommended Application

- CK410M Compliant Main Clock

Output Features

- 2 - 0.7V current-mode differential CPU pairs
- 4 - 0.7V current-mode differential PCI Express*pairs
- 1 - 0.7V current-mode differential CPU/PCI Express selectable pair
- 1 - 0.7V current-mode differential SATA pair
- 1 - 0.7V current-mode differential LCDCLK/PCI Express selectable pair
- 1 - 0.7V current-mode differential PCI Express/Clock Request pair
- 4 - PCI (33MHz)
- 2 - PCICLK_F, (33MHz) free-running
- 1 - USB, 48MHz
- 1 - DOT, 96MHz, 0.7V current differential pair
- 2 - REF, 14.318MHz

Features/Benefits

- Supports tight ppm accuracy clocks for Serial-ATA and PCI Express
- Supports programmable spread percentage and frequency
- Uses external 14.318MHz crystal, external crystal load caps are required for frequency tuning
- Supports undriven differential CPU, PCI Express pair in PD for power management.
- PEREQ# pins to support PCI Express and SATA power management.

Key Specifications

- CPU outputs cycle-cycle jitter < 85ps
- PCI Express outputs cycle-cycle jitter < 125ps
- SATA outputs cycle-cycle jitter < 125ps
- PCI outputs cycle-cycle jitter < 500ps
- ± 300ppm frequency accuracy on CPU, PCI Express and SATA clocks
- ± 100ppm frequency accuracy on USB clocks

Pin Assignment

VDDPCI1	56	PCICLK2/REQ_SEL**
GND 2	55	PCI/SRC_STOP#
PCICLK3 3	54	CPU_STOP#
PCICLK4 4	53	REF1/FS_C/TEST_SEL
PCICLK5 5	52	REF0
GND 6	51	GND
VDDPCI 7	50	X1
ITP_EN/PCICLK_F0 8	49	X2
*SELPCIEX_LCDCLK#/PCICLK_F1 9	48	VDDREF
Vtt_PwrGd#/PD 10	47	SDATA
VDD48 11	46	SCLK
FS_A/USB_48MHz 12	45	GND
GND 13	44	CPUCLKT0
DOTT_96MHz 14	43	CPUCLKC0
DOTC_96MHz 15	42	VDDCPU
FS_B/TEST_MODE 16	41	CPUCLKT1
LCDCLK_SS/PCIEX0T 17	40	CPUCLKC1
LCDCLK_SS/PCIEX0C 18	39	IREF
PCIEXT1 19	38	GNDA
PCIEXC1 20	37	VDDA
VDDPCIEX 21	36	CPUCLKT2_ITP/PCIEXT6
PCIEXT2 22	35	CPUCLKC2_ITP/PCIEXC6
PCIEXC2 23	34	VDDPCIEX
PCIEXT3 24	33	PEREQ1#/PCIEXT5
PCIEXC3 25	32	PEREQ2#/PCIEXC5
SATACLKT 26	31	PCIEXT4
SATACLKC 27	30	PCIEXC4
VDDPCIEX 28	29	GND

56-pin TSSOP

* Internal Pull-Up Resistor

** Internal Pull-Down Resistor

Functional Block Diagram

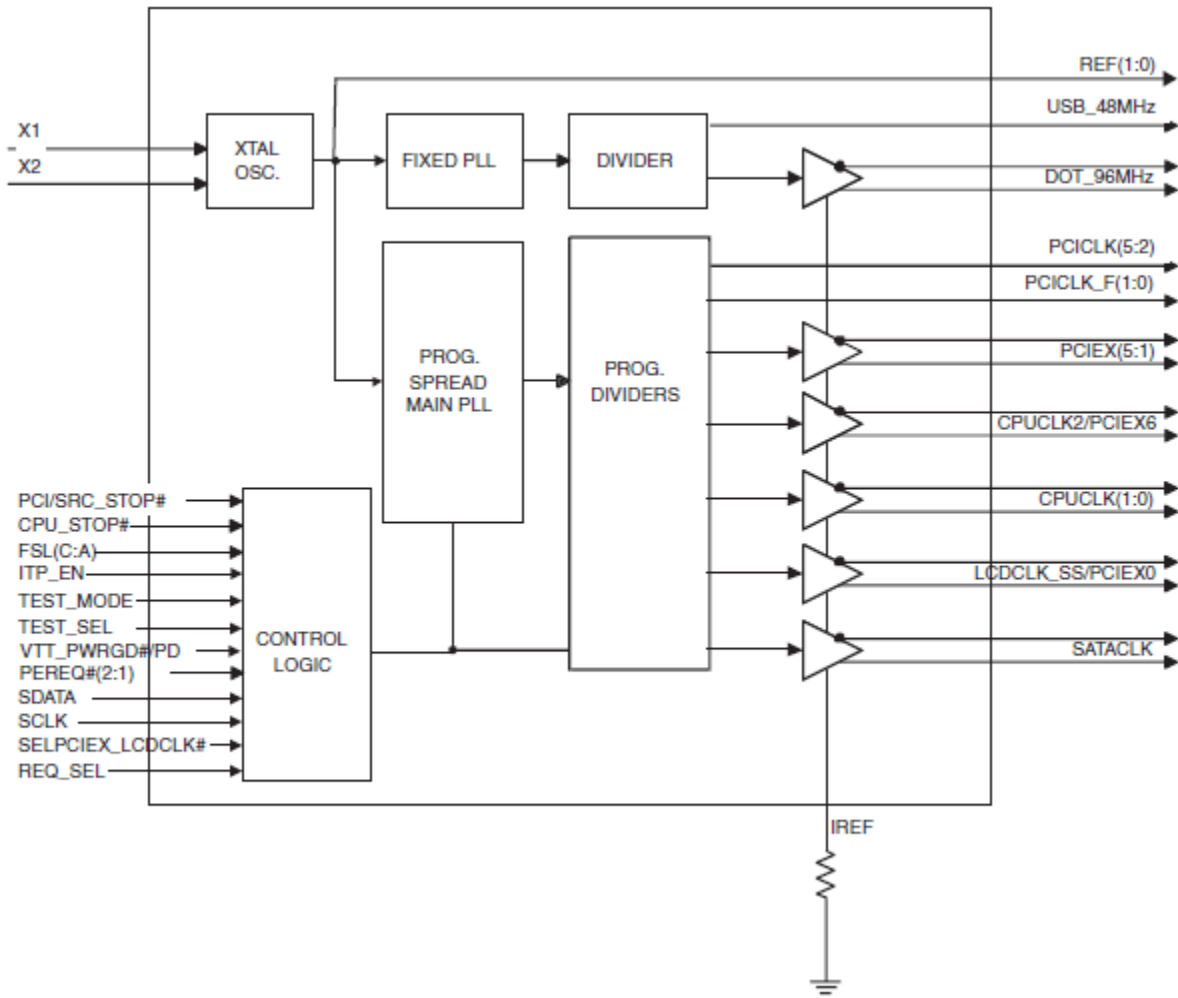


Table 1: Frequency Selection Table

FS _L C B6b2	FS _L B B6b1	FS _L A B6b0	CPU MHz	PCIEX MHz	PCI MHz	REF MHz	USB MHz	DOT MHz	Spread %
0	0	0	266.66	100.00	33.33	14.318	48.00	96.00	0.5% Down
0	0	1	133.33	100.00	33.33	14.318	48.00	96.00	0.5% Down
0	1	0	200.00	100.00	33.33	14.318	48.00	96.00	0.5% Down
0	1	1	166.66	100.00	33.33	14.318	48.00	96.00	0.5% Down
1	0	0	333.33	100.00	33.33	14.318	48.00	96.00	0.5% Down
1	0	1	100.00	100.00	33.33	14.318	48.00	96.00	0.5% Down
1	1	0	400.00	100.00	33.33	14.318	48.00	96.00	0.5% Down
1	1	1	200.00	100.00	33.33	14.318	48.00	96.00	0.5% Down

Pin Descriptions

PIN #	PIN NAME	TYPE	DESCRIPTION
1	VDDPCI	PWR	Power supply for PCI clocks, nominal 3.3V
2	GND	PWR	Ground pin.
3	PCICLK3	OUT	PCI clock output.
4	PCICLK4	OUT	PCI clock output.
5	PCICLK5	OUT	PCI clock output.
6	GND	PWR	Ground pin.
7	VDDPCI	PWR	Power supply for PCI clocks, nominal 3.3V
8	ITP_EN/PCICLK_F0	I/O	Free running PCI clock not affected by PCI_STOP# through I2C . ITP_EN: latched input to select pin functionality 1 = CPU_2_ITP pair 0 = PCIE_X_6 pair
9	*SELPCIE_X_LCDCLK#/PCICLK_F1	I/O	Latched select input for LCDCLK/PCIE_X output 0 = LCDCLK, 1 = PCIE_X / Free running 3.3V PCI clock output.
10	Vtt_PwrGd#/PD	IN	Vtt_PwrGd# is an active low input used to determine when latched inputs are ready to be sampled. PD is an asynchronous active high input pin used to put the device into a low power state. The internal clocks, PLLs and the crystal oscillator are stopped.
11	VDD48	PWR	Power pin for the 48MHz output.3.3V
12	FSLA/USB_48MHz	I/O	3.3V tolerant input for CPU frequency selection. Refer to input electrical characteristics for Vil_FS and Vih_FS values. / Fixed 48MHz USB clock output. 3.3V.
13	GND	PWR	Ground pin.
14	DOTT_96MHz	OUT	True clock of differential pair for 96.00MHz DOT clock.
15	DOTC_96MHz	OUT	Complement clock of differential pair for 96.00MHz DOT clock.
16	FSLB/TEST_MODE	IN	3.3V tolerant input for CPU frequency selection. Refer to input electrical characteristics for Vil_FS and Vih_FS values. TEST_MODE is a real time input to select between Hi-Z and REF/N divider mode while in test mode. Refer to Test Clarification Table.
17	LCDCLK_SS/PCIE_X0T	OUT	True clock of LCDCLK_SS output / True clock of PCI Express differential pair. Selected by SELPCIE_X_LCDCLK#
18	LCDCLK_SS/PCIE_X0C	OUT	Complementary clock of LCDCLK_SS output / Complementary clock of PCI Express differential pair. Selected by SELPCIE_X_LCDCLK#
19	PCIE_XT1	OUT	True clock of differential PCI_Express pair.
20	PCIE_XC1	OUT	Complement clock of differential PCI_Express pair.
21	VDDPCIE_X	PWR	Power supply for PCI Express clocks, nominal 3.3V
22	PCIE_XT2	OUT	True clock of differential PCI_Express pair.
23	PCIE_XC2	OUT	Complement clock of differential PCI_Express pair.
24	PCIE_XT3	OUT	True clock of differential PCI_Express pair.
25	PCIE_XC3	OUT	Complement clock of differential PCI_Express pair.
26	SATACLKT	OUT	True clock of differential SATA pair.
27	SATACLKC	OUT	Complement clock of differential SATA pair.
28	VDDPCIE_X	PWR	Power supply for PCI Express clocks, nominal 3.3V

Pin Descriptions (cont.)

PIN #	PIN NAME	TYPE	DESCRIPTION
29	GND	PWR	Ground pin.
30	PCIEXC4	OUT	Complement clock of differential PCI_Express pair.
31	PCIEXT4	OUT	True clock of differential PCI_Express pair.
32	PEREQ2#*/PCIEXC5	I/O	Real-time input pin that controls SATACLK and PCIEXCLK outputs that are selected through the I2c. 1 = disabled, 0 = enabled. / Complement clock of differential PCI Express output.
33	PEREQ1#*/PCIEXT5	I/O	Real-time input pin that controls SATACLK and PCIEXCLK outputs that are selected through the I2c. 1 = disabled, 0 = enabled. / True clock of differential PCI Express output.
34	VDDPCIEX	PWR	Power supply for PCI Express clocks, nominal 3.3V
35	CPUCLKC2_ITP/PCIEXC6	OUT	Complementary clock of CPU_ITP/PCIEX differential pair CPU_ITP/PCIEX output. These are current mode outputs. External resistors are required for voltage bias. Selected by ITP_EN input.
36	CPUCLKT2_ITP/PCIEXT6	OUT	True clock of differential pair CPU outputs. These are current mode outputs. External resistors are required for voltage bias. / True clock of differential PCIEX pair
37	VDDA	PWR	3.3V power for the PLL core.
38	GND A	PWR	Ground pin for the PLL core.
39	IREF	OUT	This pin establishes the reference current for the differential current-mode output pairs. This pin requires a fixed precision resistor tied to ground in order to establish the appropriate current. 475 ohms is the standard value.
40	CPUCLKC1	OUT	Complementary clock of differential pair CPU outputs. These are current mode outputs. External resistors are required for voltage bias.
41	CPUCLKT1	OUT	True clock of differential pair CPU outputs. These are current mode outputs. External resistors are required for voltage bias.
42	VDDCPU	PWR	Supply for CPU clocks, 3.3V nominal
43	CPUCLKC0	OUT	Complementary clock of differential pair CPU outputs. These are current mode outputs. External resistors are required for voltage bias.
44	CPUCLKT0	OUT	True clock of differential pair CPU outputs. These are current mode outputs. External resistors are required for voltage bias.
45	GND	PWR	Ground pin.
46	SCLK	IN	Clock pin of SMBus circuitry, 5V tolerant.
47	SDATA	I/O	Data pin for SMBus circuitry, 5V tolerant.
48	VDDREF	PWR	Ref, XTAL power supply, nominal 3.3V
49	X2	OUT	Crystal output, Nominally 14.318MHz
50	X1	IN	Crystal input, Nominally 14.318MHz.
51	GND	PWR	Ground pin.
52	REF0	OUT	14.318 MHz reference clock.
53	REF1/FSLC/TEST_SEL	I/O	14.318 MHz reference clock./ 3.3V tolerant input for CPU frequency selection. Refer to input electrical characteristics for Vil_FS and Vih_FS values. /TEST_Sel: 3-level latched input to enable test mode. Refer to Test Clarification Table
54	CPU_STOP#	IN	Stops all CPUCLK, except those set to be free running clocks
55	PCI/SRC_STOP#	IN	Stops all PCICLKs and SRCCLKs besides the free-running clocks at logic 0 level, when input low
56	PCICLK2/REQ_SEL**	I/O	3.3V PCI clock output / Latch select input pin. 0 = PCIEXCLK, 1 = PEREQ#

Table2: LCDCLK Spread and Frequency Selection Table

Byte 6b7	Byte 6b6	Byte 6b5	Byte 6b4	Byte 6b3	Pin 17/18	Spread
					MHz	%
0	0	0	0	0	96.00	0.8 Down
0	0	0	0	1	96.00	1 Down
0	0	0	1	0	96.00	1.25 Down
0	0	0	1	1	96.00	1.5 Down
0	0	1	0	0	96.00	1.75 Down
0	0	1	0	1	96.00	2 Down
0	0	1	1	0	96.00	2.5 Down
0	0	1	1	1	96.00	3 Down
0	1	0	0	0	96.00	+/-0.3 Center
0	1	0	0	1	96.00	+/-0.4 Center
0	1	0	1	0	96.00	+/-0.5 Center
0	1	0	1	1	96.00	+/-0.6 Center
0	1	1	0	0	96.00	+/-0.8 Center
0	1	1	0	1	96.00	+/-1.0 Center
0	1	1	1	0	96.00	+/-1.25 Center
0	1	1	1	1	96.00	+/-1.5 Center
1	0	0	0	0	100.00	0.8 Down
1	0	0	0	1	100.00	1 Down
1	0	0	1	0	100.00	1.25 Down
1	0	0	1	1	100.00	1.5 Down
1	0	1	0	0	100.00	1.75 Down
1	0	1	0	1	100.00	2 Down
1	0	1	1	0	100.00	2.5 Down
1	0	1	1	1	100.00	3 Down
1	1	0	0	0	100.00	+/-0.3 Center
1	1	0	0	1	100.00	+/-0.4 Center
1	1	0	1	0	100.00	+/-0.5 Center
1	1	0	1	1	100.00	+/-0.6 Center
1	1	1	0	0	100.00	+/-0.8 Center
1	1	1	0	1	100.00	+/-1.0 Center
1	1	1	1	0	100.00	+/-1.25 Center
1	1	1	1	1	100.00	+/-1.5 Center

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the 954206B. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
3.3V Core Supply Voltage	VDD_A	-			V _{DD} + 0.5V	V	1
3.3V Logic Input Supply Voltage	VDD_In	-	GND - 0.5		V _{DD} + 0.5V	V	1
Storage Temperature	Ts	-	-65		150	°C	1
Ambient Operating Temp	Tambient	-	0		70	°C	1
Case Temperature	Tcase	-			115	°C	1
Input ESD protection HBM	ESD prot	-	2000			V	1

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics – Input/Supply/Common Output Parameters

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	Notes
Input High Voltage	V_{IH}	3.3 V +/-5%	2		$V_{DD} + 0.3$	V	1
Input Low Voltage	V_{IL}	3.3 V +/-5%	$V_{SS} - 0.3$		0.8	V	1
Input High Current	I_{IH}	$V_{IN} = V_{DD}$	-5		5	uA	1
Input Low Current	I_{IL1}	$V_{IN} = 0$ V; Inputs with no pull-up resistors	-5			uA	1
	I_{IL2}	$V_{IN} = 0$ V; Inputs with pull-up resistors	-200			uA	1
Low Threshold Input-High Voltage	V_{IH_FS}	3.3 V +/-5%	0.7		$V_{DD} + 0.3$	V	1
Low Threshold Input-Low Voltage	V_{IL_FS}	3.3 V +/-5%	$V_{SS} - 0.3$		0.35	V	1
Operating Supply Current	$I_{DD3.3OP}$	Full Active, $C_L =$ Full load;		300	350	mA	1
Powerdown Current	$I_{DD3.3PD}$	all diff pairs driven		56	70	mA	1
		all differential pairs tri-stated		5	12	mA	1
Input Frequency	F_I	$V_{DD} = 3.3$ V		14.31818		MHz	2
Pin Inductance	L_{pin}				7	nH	1
Input Capacitance	C_{IN}	Logic Inputs			5	pF	1
	C_{OUT}	Output pin capacitance			6	pF	1
	C_{INX}	X1 & X2 pins			5	pF	1
Clk Stabilization	T_{STAB}	From VDD Power-Up or de-assertion of PD to 1st clock			1.8	ms	1
Modulation Frequency		Triangular Modulation	30		33	kHz	1
Tdrive_PD		CPU output enable after PD de-assertion			300	us	1
Tfall_PD		PD fall time of			5	ns	1
Trise_PD		PD rise time of			5	ns	1
SMBus Voltage	V_{DD}		2.7		5.5	V	1
Low-level Output Voltage	V_{OL}	@ I_{PULLUP}			0.4	V	1
Current sinking at $V_{OL} = 0.4$ V	I_{PULLUP}		4			mA	1
SCLK/SDATA Clock/Data Rise Time	T_{RI2C}	(Max $V_{IL} - 0.15$) to (Min $V_{IH} + 0.15$)			1000	ns	1
SCLK/SDATA Clock/Data Fall Time	T_{FI2C}	(Min $V_{IH} + 0.15$) to (Max $V_{IL} - 0.15$)			300	ns	1

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%

¹Guaranteed by design and characterization, not 100% tested in production.

²Input frequency should be measured at the REF pin and tuned to ideal 14.31818MHz to meet ppm frequency accuracy on PLL outputs.

Electrical Characteristics – CPU 0.7V Current Mode Differential Pair

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	NOTES
Current Source Output Impedance	Z _o	V _O = V _x	3000			Ω	1
Voltage High	V _{High}	Statistical measurement on single ended signal	660	766	850	mV	1,3
Voltage Low	V _{Low}		-150	21	150	mV	1,3
Max Voltage	V _{ovs}	Measurement on single ended signal using absolute value.			1150	mV	1
Min Voltage	V _{uds}		-300			mV	1
Crossing Voltage (abs)	V _{x(abs)}		250	370	550	mV	1
Crossing Voltage (var)	d-V _x	Variation of crossing over all edges			140	mV	1
Long Accuracy	ppm	see Tperiod min-max values	-300		300	ppm	1,2
Average period	T _{period}	400MHz nominal	2.4993		2.5008	ns	2
		400MHz spread	2.4993		2.5133	ns	2
		333.33MHz nominal	2.9991		3.0009	ns	2
		333.33MHz spread	2.9991		3.016	ns	2
		266.66MHz nominal	3.7489		3.7511	ns	2
		266.66MHz spread	3.7489		3.77	ns	2
		200MHz nominal	4.9985		5.0015	ns	2
		200MHz spread	4.9985		5.0266	ns	2
		166.66MHz nominal	5.9982		6.0018	ns	2
		166.66MHz spread	5.9982		6.0320	ns	2
		133.33MHz nominal	7.4978		7.5023	ns	2
		133.33MHz spread	7.4978		7.5400	ns	2
		100.00MHz nominal	9.9970		10.0030	ns	2
		100.00MHz spread	9.9970		10.0533	ns	2
Absolute min period	T _{absmin}	400MHz nominal/spread	2.4143			ns	1,2
		333.33MHz nominal/spread	2.9141			ns	1,2
		266.66MHz nominal/spread	3.6639			ns	1,2
		200MHz nominal/spread	4.8735			ns	1,2
		166.66MHz nominal/spread	5.8732			ns	1,2
		133.33MHz nominal/spread	7.3728			ns	1,2
		100.00MHz nominal/spread	9.8720			ns	1,2
Rise Time	t _r	V _{OL} = 0.175V, V _{OH} = 0.525V	175	227	700	ps	1
Fall Time	t _f	V _{OH} = 0.525V V _{OL} = 0.175V	175	227	700	ps	1
Rise Time Variation	d-t _r	V _{OL} = 0.175V, V _{OH} = 0.525V		32	125	ps	1
Fall Time Variation	d-t _f	V _{OH} = 0.525V V _{OL} = 0.175V		37	125	ps	1
Duty Cycle	d ₁₃	Measurement from differential waveform	45	51	55	%	1
Skew	t _{sk3}	CPU(1:0), V _T = 50%		28	100	ps	1
Skew	t _{sk4}	CPU(1:0) to CPU2_ITP, V _T = 50%		105	150	ps	1
Jitter, Cycle to cycle	t _{j_{cyc-cyc}}	Measurement from differential waveform (CPU2_ITP)		65	125	ps	1
Jitter, Cycle to cycle	t _{j_{cyc-cyc}}	Measurement from differential waveform, (CPU(1:0))		50	85	ps	1

*TA - 0 - 70°C; V_{DD} = 3.3V +/-5%; C_L = 2pF, R_S=33.2Ω, R_P=49.9Ω, I_{REF}=475Ω

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy and Clock Period specifications are guaranteed assuming that REFOUT is at 14.31818MHz

³I_{REF} = V_{DD}/(3xR_R). For R_R = 475Ω (1%), I_{REF} = 2.32mA. I_{OH} = 6 x I_{REF} and V_{OH} = 0.7V @ Z_O=50Ω.

Electrical Characteristics – SRC/SATA/PCIE X 0.7V Current Mode Differential Pair

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	Notes
Current Source Output Impedance	Z _o	V _O = V _x	3000			Ω	1
Voltage High	V _{High}	Statistical measurement on single ended signal	660	780	850	mV	1,3
Voltage Low	V _{Low}		-150	-15	150	mV	1,3
Max Voltage	V _{ovs}	Measurement on single ended signal using absolute value.			1150	mV	1
Min Voltage	V _{uds}		-300			mV	1
Crossing Voltage (abs)	V _{x(abs)}		250	360	550	mV	1
Crossing Voltage (var)	d-V _x	Variation of crossing over all edges		50	140	mV	1
Long Accuracy	ppm	see Tperiod min-max values	-300		300	ppm	1,2
Average period	Tperiod	100.00MHz nominal	9.9970		10.0030	ns	2
		100.00MHz spread	9.9970		10.0533	ns	2
Absolute min period	Tabsmin	100.00MHz nominal/spread	9.8720			ns	1,2
Rise Time	t _r	V _{OL} = 0.175V, V _{OH} = 0.525V	175	228	700	ps	1
Fall Time	t _f	V _{OH} = 0.525V V _{OL} = 0.175V	175	221	700	ps	1
Rise Time Variation	d-t _r	V _{OL} = 0.175V, V _{OH} = 0.525V		18	125	ps	1
Fall Time Variation	d-t _f	V _{OH} = 0.525V V _{OL} = 0.175V		41	125	ps	1
Duty Cycle	d ₁₃	Measurement from differential waveform	45	51	55	%	1
Skew	t _{sk3}	V _T = 50%		135	250	ps	1
Jitter, Cycle to cycle	t _{jcy-cyc}	Measurement from differential waveform		55	125	ps	1

*T_A = 0 - 70°C; V_{DD} = 3.3 V +/-5%; C_L = 2pF, R_S = 33.2Ω, R_P = 49.9Ω, I_{REF} = 475Ω

¹Guaranteed by design and characterization, not 100% tested in production.

²All Long Term Accuracy and Clock Period specifications are guaranteed assuming that REFOUT is at 14.31818MHz

³I_{REF} = V_{DD}/(3xR_R). For R_R = 475Ω (1%), I_{REF} = 2.32mA. I_{OH} = 6 x I_{REF} and V_{OH} = 0.7V @ Z_O = 50Ω.

Electrical Characteristics – PCICLK/PCICLK_F

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	NOTES
Output Impedance	R _{DSP}	V _O = V _{DD} *(0.5)	12		55	Ω	1
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4			V	1
Output Low Voltage	V _{OL}	I _{OL} = 1 mA			0.55	V	1
Output High Current	I _{OH}	V _{OH} @ MIN = 1.0 V	-33			mA	1
		V _{OH} @ MAX = 3.135 V			-33	mA	1
Output Low Current	I _{OL}	V _{OL} @ MIN = 1.95 V	30			mA	1
		V _{OL} @ MAX = 0.4 V			38	mA	1
Edge Rate	t _{slewr/f}	Rising/Falling edge rate	1	1.5	4	V/ns	1
Rise Time	t _r	V _{OL} = 0.4 V, V _{OH} = 2.4 V	0.5	1.26	2	ns	1
Fall Time	t _f	V _{OH} = 2.4 V, V _{OL} = 0.4 V	0.5	1.34	2	ns	1
Duty Cycle	d ₁₁	V _T = 1.5 V	45	50	55	%	1
Group Skew	t _{skew}	V _T = 1.5 V		25	250	ps	1
Jitter, Cycle to cycle	t _{jcy-cyc}	V _T = 1.5 V		112	500	ps	1

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%, CL = 20 pF with R_s = 7Ω (unless otherwise specified)

¹Guaranteed by design and characterization, not 100% tested in production.

³Spread Spectrum is off

Electrical Characteristics – USB48MHz

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	NOTES
Long Accuracy	ppm	see Tperiod min-max values	-100		100	ppm	1,2
Clock period	T _{period}	48.00MHz output nominal	20.8313		20.8354	ns	2
Output Impedance	R _{DSP}	V _O = V _{DD} *(0.5)	12		55	Ω	1
Output High Voltage	V _{OH}	I _{OH} = -1 mA	2.4			V	1
Output Low Voltage	V _{OL}	I _{OL} = 1 mA			0.55	V	1
Output High Current	I _{OH}	V _{OH} @ MIN = 1.0 V	-33			mA	1
		V _{OH} @ MAX = 3.135 V			-33	mA	1
Output Low Current	I _{OL}	V _{OL} @ MIN = 1.95 V	30			mA	1
		V _{OL} @ MAX = 0.4 V			38	mA	1
Edge Rate	t _{slewr/f_USB}	USB48 Rising/Falling edge rate	1	1.5	2	V/ns	1
Rise Time	t _{r_USB}	V _{OL} = 0.4 V, V _{OH} = 2.4 V	1	1.26	2	ns	1
Fall Time	t _{f_USB}	V _{OH} = 2.4 V, V _{OL} = 0.4 V	1	1.34	2	ns	1
Duty Cycle	d _{t1}	V _T = 1.5 V	45	51.6	55	%	1
Group Skew	t _{skew}	V _T = 1.5 V			250	ps	1
Jitter, Cycle to cycle	t _{jyc-cyc}	V _T = 1.5 V		228	500	ps	1

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%, CL = 20 pF with Rs = 7Ω (Rs is used in USB48MHz test only)

¹Guaranteed by design and characterization, not 100% tested in production.

Electrical Characteristics – DOT_96MHz 0.7V Current Mode Differential Pair

PARAMETER	SYMBOL	CONDITIONS*	MIN	TYP	MAX	UNITS	Notes
Current Source Output Impedance	Z _o	V _O = V _x	3000			Ω	1
Voltage High	VHigh	Statistical measurement on single ended signal	660	780	850	mV	1,3
Voltage Low	VLow		-150	0	150	mV	1,3
Max Voltage	Vovs	Measurement on single ended signal using absolute value.			1150	mV	1
Min Voltage	Vuds		-300			mV	1
Crossing Voltage (abs)	Vx(abs)		250		550	mV	1
Crossing Voltage (var)	d-Vcross	Variation of crossing over all edges			140	mV	1
Long Accuracy	ppm	see Tperiod min-max values	-100		100	ppm	1,2
Average period	Tperiod	96.00MHz nominal	10.4135		10.4198	ns	2
Absolute min period	Tabsmn	96.00MHz nominal	10.1635			ns	1,2
Rise Time	t _r	V _{OL} = 0.175V, V _{OH} = 0.525V	175	228	700	ps	1
Fall Time	t _f	V _{OH} = 0.525V V _{OL} = 0.175V	175	221	700	ps	1
Rise Time Variation	d-t _r	V _{OL} = 0.175V, V _{OH} = 0.525V		21	125	ps	1
Fall Time Variation	d-t _f	V _{OH} = 0.525V V _{OL} = 0.175V		18	125	ps	1
Duty Cycle	d _{t3}	Measurement from differential waveform	45	49.8	55	%	1
Jitter, Cycle to cycle	t _{jyc-cyc}	Measurement from differential waveform		120	250	ps	1

*T_A = 0 - 70°C; V_{DD} = 3.3 V +/-5%; C_L = 2pF, R_S = 33.2Ω, R_P = 49.9Ω, I_{REF} = 475Ω

¹Guaranteed by design and characterization, not 100% tested in production.

² All Long Term Accuracy and Clock Period specifications are guaranteed assuming that REFOUT is at 14.31818MHz

³I_{REF} = V_{DD}/(3xR_R). For R_R = 475Ω (1%), I_{REF} = 2.32mA. I_{OH} = 6 x I_{REF} and V_{OH} = 0.7V @ Z_O = 50Ω.

Electrical Characteristics – REF-14.318MHz

PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	UNITS	Notes
Long Accuracy	ppm	see Tperiod min-max values	-300		300	ppm	1,2
Clock period	T_{period}	14.318MHz output nominal	69.8270		69.8550	ns	2
Output High Voltage	V_{OH}	$I_{\text{OH}} = -1 \text{ mA}$	2.4			V	1
Output Low Voltage	V_{OL}	$I_{\text{OL}} = 1 \text{ mA}$			0.4	V	1
Output High Current	I_{OH}	$V_{\text{OH}} @ \text{MIN} = 1.0 \text{ V},$ $V_{\text{OH}} @ \text{MAX} = 3.135 \text{ V}$	-29		-23	mA	1
Output Low Current	I_{OL}	$V_{\text{OL}} @ \text{MIN} = 1.95 \text{ V},$ $V_{\text{OL}} @ \text{MAX} = 0.4 \text{ V}$	29		27	mA	1
Edge Rate	t_{slewrf}	Rising/Falling edge rate	1	2	4	V/ns	1
Rise Time	t_{r1}	$V_{\text{OL}} = 0.4 \text{ V}, V_{\text{OH}} = 2.4 \text{ V}$	0.5	1.6	2	ns	1
Fall Time	t_{f1}	$V_{\text{OH}} = 2.4 \text{ V}, V_{\text{OL}} = 0.4 \text{ V}$	0.5	2	2	ns	1
Skew	t_{sk1}	$V_{\text{T}} = 1.5 \text{ V}$			500	ps	1
Duty Cycle	d_{t1}	$V_{\text{T}} = 1.5 \text{ V}$	45	53	55	%	1
Jitter	$t_{\text{jvc-cvc}}$	$V_{\text{T}} = 1.5 \text{ V}$		750	1000	ps	1

*TA = 0 - 70°C; Supply Voltage VDD = 3.3 V +/-5%, CL = 20 pF with Rs = 7Ω (Rs is used in USB48MHz test only)

¹Guaranteed by design and characterization, not 100% tested in production.

²All Long Term Accuracy and Clock Period specifications are guaranteed assuming that REFOUT is at 14.31818MHz

General SMBus Serial Interface Information for 954206B

How to Write

- Controller (host) sends a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) sends the byte count = X
- IDT clock will **acknowledge**
- Controller (host) starts sending Byte **N through Byte N+X-1**
- IDT clock will **acknowledge** each byte **one at a time**
- Controller (host) sends a Stop bit

Index Block Write Operation		
Controller (Host)		IDT (Slave/Receiver)
T	starT bit	
Slave Address		
WR	WRite	
		ACK
Beginning Byte = N		
		ACK
Data Byte Count = X		
		ACK
Beginning Byte N		
		ACK
O	X Byte	O
O		O
O		O
Byte N + X - 1		
		ACK
P	stoP bit	

Read Address	Write Address
D3 _(H)	D2 _(H)

How to Read

- Controller (host) will send a start bit
- Controller (host) sends the write address
- IDT clock will **acknowledge**
- Controller (host) sends the beginning byte location = N
- IDT clock will **acknowledge**
- Controller (host) will send a separate start bit
- Controller (host) sends the read address
- IDT clock will **acknowledge**
- IDT clock will send the data byte count = X
- IDT clock sends Byte **N+X-1**
- IDT clock sends **Byte 0 through Byte X (if X_(H) was written to Byte 8)**
- Controller (host) will need to acknowledge each byte
- Controller (host) will send a not acknowledge bit
- Controller (host) will send a stop bit

Index Block Read Operation		
Controller (Host)		IDT (Slave/Receiver)
T	starT bit	
Slave Address		
WR	WRite	
		ACK
Beginning Byte = N		
		ACK
RT	Repeat starT	
Slave Address		
RD	ReaD	
		ACK
		Data Byte Count=X
ACK		
ACK		Beginning Byte N
O	X Byte	O
O		O
O		O
		Byte N + X - 1
N	Not acknowledge	
P	stoP bit	

I²C Table: Output Control Register

Byte 0		Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-		CPUCLK2_ITP/PCIEX6 Enable	Output Enable	RW	Disable	Enable	1
Bit 6	-		PCIEX5 Enable	Output Enable	RW	Disable	Enable	1
Bit 5	-		PCIEX4 Enable	Output Enable	RW	Disable	Enable	1
Bit 4	-		SATACLK Enable	Output Enable	RW	Disable	Enable	1
Bit 3	-		PCIEX3 Enable	Output Enable	RW	Disable	Enable	1
Bit 2	-		PCIEX2 Enable	Output Enable	RW	Disable	Enable	1
Bit 1	-		PCIEX1 Enable	Output Enable	RW	Disable	Enable	1
Bit 0	-		LCDCLK/PCIEX0 Enable	Output Enable	RW	Disable	Enable	1

I²C Table: Spread and Output Control Register

Byte 1		Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-		Test Clock Mode Entry	Test Mode	RW	Disable	Enable	0
Bit 6	-		DOT_96MHz Enable	Output Enable	RW	Disable	Enable	1
Bit 5	-		USB_48MHz Enable	Output Enable	RW	Disable	Enable	1
Bit 4	-		REF_0 Enable	Output Enable	RW	Disable	Enable	1
Bit 3	-		LCDCLK/PCIEX0 Spectrum Mode	Spread Control	RW	OFF	ON	1
Bit 2	-		CPUCLK1	Output Enable	RW	Disable	Enable	1
Bit 1	-		CPUCLK0	Output Enable	RW	Disable	Enable	1
Bit 0	-		Spread Spectrum Mode	Spread Control for PLL1	RW	OFF	ON	0

I²C Table: Output Control Register

Byte 2		Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-		PCICLK5	Output Enable	RW	Disable	Enable	1
Bit 6	-		PCICLK4	Output Enable	RW	Disable	Enable	1
Bit 5	-		PCICLK3	Output Enable	RW	Disable	Enable	1
Bit 4	-		PCICLK2	Output Enable	RW	Disable	Enable	1
Bit 3	-		Test Mode Selection	Test Mode Selection	RW	Hi-Z	REF/N	0
Bit 2	-		PCI_STOP	Stop all PCI, PCIEX and SATA clocks	RW	Enable	Disable	1
Bit 1	-		PCI_F0 Enable	Output Enable	RW	Disable	Enable	1
Bit 0	-		PCI_F1 Enable	Output Enable	RW	Disable	Enable	1

I²C Table: Output Control Register

Byte 3		Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-		PCIEX6	Allow assertion of PCI_STOP# or setting of PCI_STOP control bit in SMBus register to stop PCIEX clocks	RW	Free Running	Stoppable	0
Bit 6	-		PCIEX5		RW	Free Running	Stoppable	0
Bit 5	-		PCIEX4		RW	Free Running	Stoppable	0
Bit 4	-		SATACLK		RW	Free Running	Stoppable	0
Bit 3	-		PCIEX3		RW	Free Running	Stoppable	0
Bit 2	-		PCIEX2		RW	Free Running	Stoppable	1
Bit 1	-		PCIEX1		RW	Free Running	Stoppable	1
Bit 0	-		PCIEX0		RW	Free Running	Stoppable	1

I²C Table: Output Control Register

Byte 4	Pin #	Name	Control	Type	0	1	PWD
			Function				
Bit 7	-	REF_1 Enable	Output Enable	RW	Disable	Enable	1
Bit 6	-	96MHz	Driven in PD	RW	Driven	Hi-Z	1
Bit 5	-	REF_0 STRENGTH	Strength Programming	RW	1X	2X	1
Bit 4	-	PCL_F1	Allow assertion of PCL_STOP# or setting of	RW	Free Running	Stoppable	1
Bit 3	-	PCL_F0		RW	Free Running	Stoppable	1
Bit 2	-	CPUCLK2_ITP	Allow assertion of CPU_STOP# to stop CPUCLK outputs	RW	Free Running	Stoppable	1
Bit 1	-	CPUCLK1		RW	Free Running	Stoppable	1
Bit 0	-	CPUCLK0		RW	Free Running	Stoppable	1

I²C Table: Output Control Register

Byte 5	Pin #	Name	Control	Type	0	1	PWD
			Function				
Bit 7	-	PCI_STOP Drive Mode	Driven in PCI_STOP#	RW	Driven	Hi-Z	0
Bit 6	-	CPUCLK2_ITP_STOP Drive Mode	Driven in CPU_STOP#	RW	Driven	Hi-Z	0
Bit 5	-	CPUCLK1_STOP Drive Mode		RW	Driven	Hi-Z	0
Bit 4	-	CPUCLK0_STOP Drive Mode		RW	Driven	Hi-Z	0
Bit 3	-	PCIEX (6:0) Drive Mode	Driven in Powerdown (PD)	RW	Driven	Hi-Z	0
Bit 2	-	CPUCLK2_ITP_PD Drive Mode		RW	Driven	Hi-Z	0
Bit 1	-	CPUCLK[1:0] PD Drive Mode		RW	Driven	Hi-Z	0
Bit 0	-	ITP_EN	PCIEX/CPU_ITP select	RW	PCIEX	CPU_ITP	latch

I²C Table: Output Control Register

Byte 6	Pin #	Name	Control	Type	0	1	PWD
			Function				
Bit 7	-	SS4	LCDCLK Spread Prog Bit 4	RW	96Mhz	100Mhz	0
Bit 6	-	SS3	LCDCLK Spread Prog Bit 3	RW	See Table 2: LCDCLK Freq Sel		1
Bit 5	-	SS2	LCDCLK Spread Prog Bit 2	RW			0
Bit 4	-	SS1	LCDCLK Spread Prog Bit 1	RW			0
Bit 3	-	SS0	LCDCLK Spread Prog Bit 0	RW			0
Bit 2	-	FSLC	Freq Select Bit 2	RW	See Table 1: PLL1 Frequency Selection Table		Latched
Bit 1	-	FSLB	Freq Select Bit 1	RW			Latched
Bit 0	-	FSLA	Freq Select Bit 0	RW			Latched

I²C Table: Vendor & Revision ID Register

Byte 7	Pin #	Name	Control	Type	0	1	PWD
			Function				
Bit 7	-	RID3	REVISION ID	R	-	-	x
Bit 6	-	RID2		R	-	-	x
Bit 5	-	RID1		R	-	-	x
Bit 4	-	RID0		R	-	-	x
Bit 3	-	VID3	VENDOR ID	R	-	-	0
Bit 2	-	VID2		R	-	-	0
Bit 1	-	VID1		R	-	-	0
Bit 0	-	VID0		R	-	-	1

I²C Table: Byte Count Register

Byte 8	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	BC7	Byte Count Programming b(7:0)	RW	Writing to this register will configure how many bytes will be read back, default is 0F = 15 bytes.		0
Bit 6	-	BC6		RW			0
Bit 5	-	BC5		RW			0
Bit 4	-	BC4		RW			0
Bit 3	-	BC3		RW			1
Bit 2	-	BC2		RW			1
Bit 1	-	BC1		RW			1
Bit 0	-	BC0		RW			1

I²C Table: Watchdog Timer Register

Byte 9	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	WDH_EN	Watchdog Hard Alarm Enable	RW	Disable	Enable	0
Bit 6	-	WDS_EN	Watchdog Soft Alarm Enable	RW	Disable	Enable	0
Bit 5	-	WD Hard Status	WD Hard Alarm Status	R	Normal	Alarm	X
Bit 4	-	WD Soft Status	WD Soft Alarm Status	R	Normal	Alarm	X
Bit 3	-	WDTCtrl	Watch Dog Time base Control	RW	290ms Base	1160ms Base	0
Bit 2	-	WD2	WD Timer Bit 2	RW	These bits represent X*290ms (or 1.16S) the watchdog timer waits before it goes to alarm mode. Default is 7 X 290ms = 2s.		1
Bit 1	-	WD1	WD Timer Bit 1	RW			1
Bit 0	-	WD0	WD Timer Bit 0	RW			1

I²C Table: VCO Control Select Bit & WD Timer Control Register

Byte 10	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	M/N_EN	PLL/M/N Programming Enable	RW	Disable	Enable	0
Bit 6	-	LCDCLK/PCIEX0 SEL	SELPCIEX0/LCDCLK#	RW	LCDCLK	PCIEX0	latch
Bit 5	-	REQ_SEL	REQ_SEL	RW	PCIEX5	PEREQ	latch
Bit 4	-	LCDCLK/PCIEX0	Driven in PD	RW	Driven	Hi-Z	0
Bit 3	-	WD Safe Freq Source	WD Safe Freq Source	RW	Latch Inputs/Byte6[2:0]	B10b(2:0)	0
Bit 2	-	WD SFC	Watch Dog Safe Freq Programming bits	RW	Writing to these bit will configure the safe frequency as Byte0 bit (4:0).		0
Bit 1	-	WD SFB		RW			0
Bit 0	-	WD SFA		RW			0

I²C Table: VCO Frequency Control Register

Byte 11	Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-	N Div8	N Divider Prog bit 8	RW	The decimal representation of M and N Divider in Byte 11 and 12 will configure the VCO frequency. Default at power up = latch-in or Byte 0 Rom table. VCO Frequency = $14.318 \times [\text{NDiv}(9:0)+8] / [\text{MDiv}(5:0)+2]$		X
Bit 6	-	N Div 9	N Divider Prog bit 9	RW			X
Bit 5	-	M Div5	M Divider Programming bits	RW			X
Bit 4	-	M Div4		RW			X
Bit 3	-	M Div3		RW			X
Bit 2	-	M Div2		RW			X
Bit 1	-	M Div1		RW			X
Bit 0	-	M Div0		RW			X

I²C Table: VCO Frequency Control Register

Byte 12		Pin #	Name	Control Function	Type	0		1		PWD
Bit 7	-	-	N Div7	N Divider Programming b(8:0)	RW	The decimal representation of M and N Divier in Byte 11 and 12 will configure the VCO frequency. Default at power up = latch-in or Byte 0 Rom table. VCO Frequency = 14.318 x [NDiv(9:0)+8] / [MDiv(5:0)+2]				X
Bit 6	-	-	N Div6		RW					X
Bit 5	-	-	N Div5		RW					X
Bit 4	-	-	N Div4		RW					X
Bit 3	-	-	N Div3		RW					X
Bit 2	-	-	N Div2		RW					X
Bit 1	-	-	N Div1		RW					X
Bit 0	-	-	N Div0		RW					X

I²C Table: Spread Spectrum Control Register

Byte 13		Pin #	Name	Control Function	Type	0		1		PWD
Bit 7	-	-	SSP7	Spread Spectrum Programming b(7:0)	RW	These Spread Spectrum bits in Byte 13 and 14 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.				X
Bit 6	-	-	SSP6		RW					X
Bit 5	-	-	SSP5		RW					X
Bit 4	-	-	SSP4		RW					X
Bit 3	-	-	SSP3		RW					X
Bit 2	-	-	SSP2		RW					X
Bit 1	-	-	SSP1		RW					X
Bit 0	-	-	SSP0		RW					X

I²C Table: Spread Spectrum Control Register

Byte 14		Pin #	Name	Control Function	Type	0		1		PWD
Bit 7	-	-	Reserved	Reserved	R	-	-	-	-	0
Bit 6	-	-	SSP14	Spread Spectrum Programming b(14:8)	RW	These Spread Spectrum bits in Byte 13 and 14 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.				X
Bit 5	-	-	SSP13		RW					X
Bit 4	-	-	SSP12		RW					X
Bit 3	-	-	SSP11		RW					X
Bit 2	-	-	SSP10		RW					X
Bit 1	-	-	SSP9		RW					X
Bit 0	-	-	SSP8		RW					X

I²C Table: Output Divider Control Register

Byte 15		Pin #	Name	Control Function	Type	0		1		PWD
Bit 7	-	-	PCIEX Div3	PCIEX Divider Ratio Programming Bits	RW	0000:/2	0100:/4	1000:/8	1100:/16	X
Bit 6	-	-	PCIEX Div2		RW	0001:/3	0101:/6	1001:/12	1101:/24	X
Bit 5	-	-	PCIEX Div1		RW	0010:/5	0110:/10	1010:/20	1110:/40	X
Bit 4	-	-	PCIEX Div0		RW	0011:/15	0111:/30	1011:/60	1111:/120	X
Bit 3	-	-	CPU Div3	CPUDivider Ratio Programming Bits	RW	0000:/2	0100:/4	1000:/8	1100:/16	X
Bit 2	-	-	CPU Div2		RW	0001:/3	0101:/6	1001:/12	1101:/24	X
Bit 1	-	-	CPU Div1		RW	0010:/5	0110:/10	1010:/20	1110:/40	X
Bit 0	-	-	CPU Div0		RW	0011:/15	0111:/30	1011:/60	1111:/120	X

I²C Table: PEREQ# Control Register

Byte 16		Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-		Reserved	Reserved	RW	-	-	0
Bit 6	-		PEREQ2# controls selected outputs. Outputs controlled by this pin will be Hi-Z when PEREQ2# is high.	PCIEX4 is controlled	RW	Not Controlled	Controlled	1
Bit 5	-			PCIEX3 is controlled	RW	Not Controlled	Controlled	0
Bit 4	-			PCIEX1 is controlled	RW	Not Controlled	Controlled	0
Bit 3	-		Reserved	Reserved	RW	-	-	0
Bit 2	-		PEREQ1# controls selected outputs. Outputs controlled by this pin will be Hi-Z when PEREQ1# is high.	SATACLK is controlled	RW	Not Controlled	Controlled	1
Bit 1	-			PCIEX2 is controlled	RW	Not Controlled	Controlled	0
Bit 0	-			PCIEX0 is controlled	RW	Not Controlled	Controlled	0

I²C Table: PLL 2 VCO Frequency Control Register

Byte 17		Pin #	Name	Control Function	Type	0	1	PWD	
Bit 7	-		N Div8	N Divider Prog bit 8	RW	The decimal representation of M and N Divier in Byte 17 and 18 will configure the VCO frequency. Default at power up = Byte 0 Rom table. VCO Frequency = $14.318 \times [\text{NDiv}(9:0)+8] / [\text{MDiv}(5:0)+2]$		X	
Bit 6	-		N Div9	N Divider Prog bit 9	RW			X	
Bit 5	-		M Div5	M Divider Programming bits	RW			X	
Bit 4	-				M Div4			RW	X
Bit 3	-				M Div3			RW	X
Bit 2	-				M Div2			RW	X
Bit 1	-		M Div1	RW	X				
Bit 0	-		M Div0	RW	X				

I²C Table: PLL 2 VCO Frequency Control Register

Byte 18		Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-		N Div7	N Divider Programming b(8:0)	RW	The decimal representation of M and N Divier in Byte 17 and 18 will configure the VCO frequency. Default at power up = Byte 0 Rom table. VCO Frequency = $14.318 \times [\text{NDiv}(9:0)+8] / [\text{MDiv}(5:0)+2]$		X
Bit 6	-		N Div6		RW			X
Bit 5	-		N Div5		RW			X
Bit 4	-		N Div4		RW			X
Bit 3	-		N Div3		RW			X
Bit 2	-		N Div2		RW			X
Bit 1	-		N Div1		RW			X
Bit 0	-		N Div0		RW			X

I²C Table: PLL 2 Spread Spectrum Control Register

Byte 19		Pin #	Name	Control Function	Type	0	1	PWD
Bit 7	-		SSP7	Spread Spectrum Programming b(7:0)	RW	These Spread Spectrum bits in Byte 19 and 20 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.		X
Bit 6	-		SSP6		RW			X
Bit 5	-		SSP5		RW			X
Bit 4	-		SSP4		RW			X
Bit 3	-		SSP3		RW			X
Bit 2	-		SSP2		RW			X
Bit 1	-		SSP1		RW			X
Bit 0	-		SSP0		RW			X

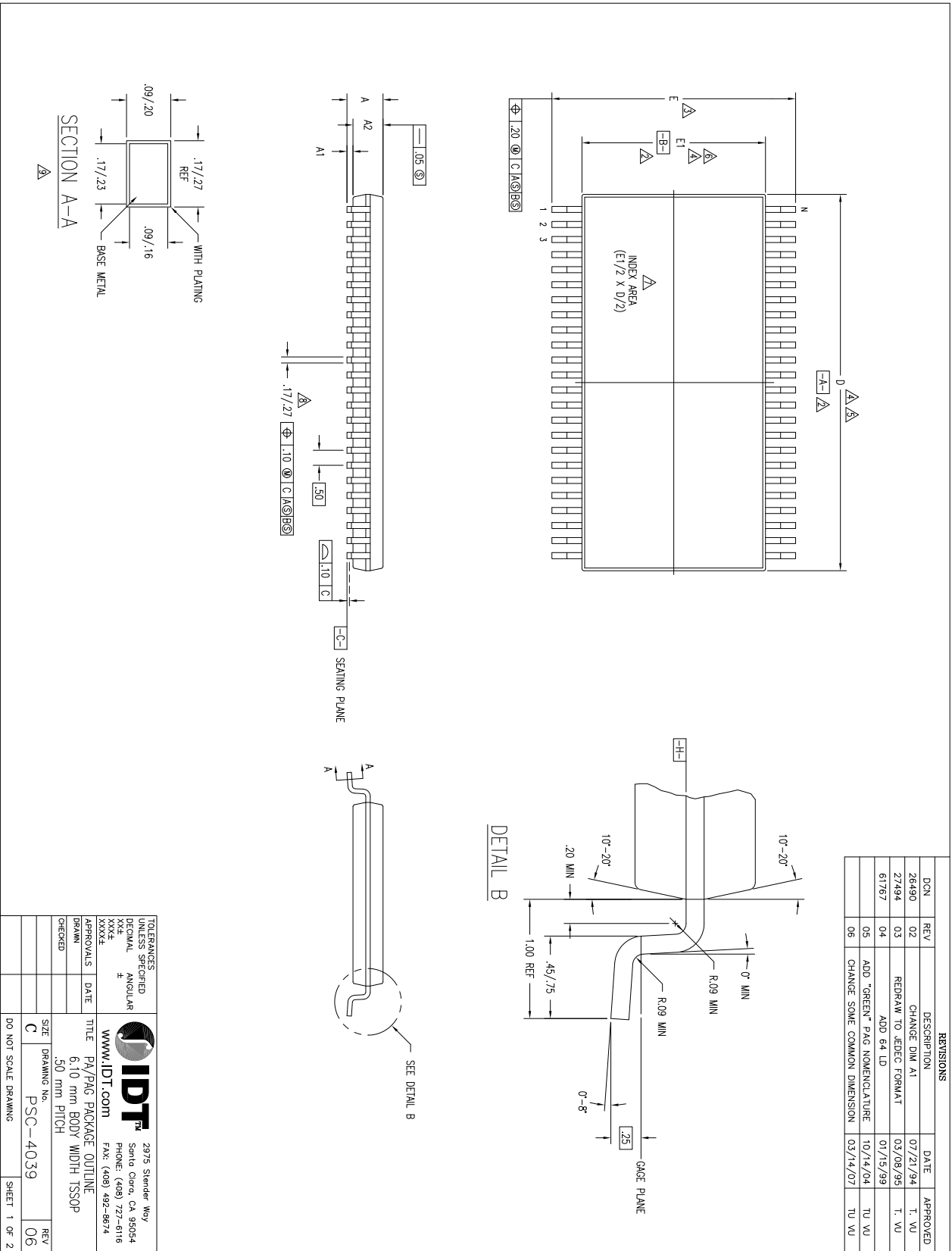
I²C Table: PLL2 Spread Spectrum Control Register

Byte 20	Pin #	Name	Control	Type	0	1	PWD
			Function				
Bit 7	-	Reserved	Reserved	R	-	-	0
Bit 6	-	SSP14	Spread Spectrum Programming b(14:8)	RW	These Spread Spectrum bits in Byte 19 and 20 will program the spread percentage. It is recommended to use ICS Spread % table for spread programming.		X
Bit 5	-	SSP13		RW			X
Bit 4	-	SSP12		RW			X
Bit 3	-	SSP11		RW			X
Bit 2	-	SSP10		RW			X
Bit 1	-	SSP9		RW			X
Bit 0	-	SSP8		RW			X

Test Clarification Table

Comments	HW		SW		OUTPUT
	FSLC/TEST_SEL HW PIN	FSLB/TEST_MODE HW PIN	TEST ENTRY BIT W1b7	REF/N or HI-Z W2b3	
		0	X	0	
Power-up w/ TEST_SEL = 1 to enter test mode Cycle power to disable test mode FSLC./TEST_SEL -->3-level latched input If power-up w/ V>2.0V (-0.3V) then use TEST_SEL If power-up w/ V<2.0V (-0.3V) then use FSLC FSLB/TEST_MODE -->low Vth input TEST_MODE is a	1	0	X	0	HI-Z
	1	0	X	1	REF/N
	1	1	X	0	REF/N
If TEST_SEL HW pin is 0 during power-up, test mode can be invoked through W1b7. If test mode is invoked by W1b7, only W2b3 is used to select HI-Z or REF/N FSLB/TEST_Mode pin is not used. Cycle power to disable test mode, one shot control	1	1	X	1	REF/N
	0	X	1	0	HI-Z
	0	X	1	1	REF/N
W1b7: 1= ENTER TEST MODE, Default = 0 (NORMAL OPERATION)					
W2b3: 1= REF/N, Default = 0 (HI-Z)					

Package Outline and Dimensions (56-pin TSSOP)



Package Outline and Dimensions, cont. (56-pin TSSOP)

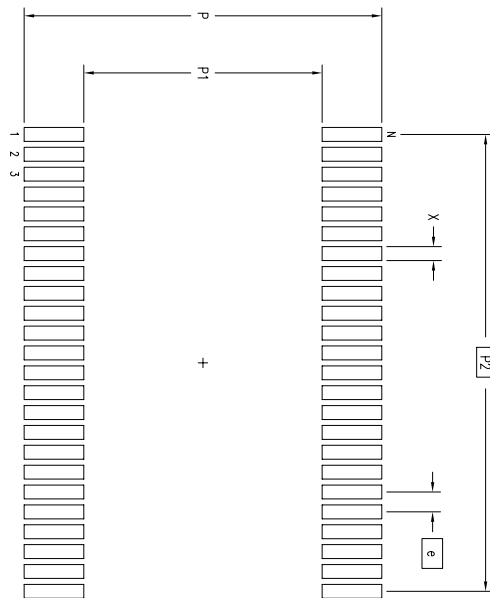
SYMBOL	JEDEC VARIATION			N D T E	JEDEC VARIATION			N D T E	JEDEC VARIATION			N D T E
	ED	NOM	MAX		EE	NOM	MAX		EF	NOM	MAX	
A	—	1.20	—	—	—	1.20	—	—	—	1.20	—	—
A1	.05	.15	.15	.05	.15	.15	.05	.15	.15	.15	.15	.15
A2	.80	1.00	1.05	.80	1.00	1.05	.80	1.00	1.05	1.05	1.05	1.05
D	12.40	12.50	12.60	4.5	13.90	14.00	14.10	4.5	16.90	17.00	17.10	4.5
E	7.95	8.10	8.25	3	7.95	8.10	8.25	3	7.95	8.10	8.25	3
E1	6.00	6.10	6.20	4.6	6.00	6.10	6.20	4.6	6.00	6.10	6.20	4.6
N	48			56			64			64		

NOTES:

- ALL DIMENSIONING AND TOLERANCING CONFORM TO ANSI Y14.5M-1982
- DATUMS **-A-** AND **-B-** TO BE DETERMINED AT DATUM PLANE **-H-**
- DIMENSION E TO BE DETERMINED AT SEATING PLANE **-C-**
- DIMENSIONS D AND E1 ARE TO BE DETERMINED AT DATUM PLANE **-H-**
- DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED .15 mm PER SIDE
- DIMENSION E1 DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS. INTERLEAD FLASH OR PROTRUSIONS SHALL NOT EXCEED .25 mm PER SIDE
- DETAIL OF PIN 1 IDENTIFIER IS OPTIONAL BUT MUST BE LOCATED WITHIN THE ZONE INDICATED
- LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION IS .08 mm IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT
- THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .10 AND .25 mm FROM THE LEAD TIP
- ALL DIMENSIONS ARE IN MILLIMETERS
- THIS OUTLINE CONFORMS TO JEDEC PUBLICATION 95 REGISTRATION MO-153, VARIATION ED, EE & EF

REVISIONS				
DCN	REV	DESCRIPTION	DATE	APPROVED
26490	02	CHANGE DIM A1	07/21/94	T. VU
27494	03	REDRAW TO JEDEC FORMAT	03/08/95	T. VU
61767	04	ADD 64 LD	01/15/99	TU VU
05	05	ADD "GREEN" PAG NOMENCLATURE	10/14/04	TU VU
06	06	CHANGE SOME COMMON DIMENSION	03/14/07	TU VU

LAND PATTERN DIMENSIONS



	MIN	MAX	MIN	MAX	MIN	MAX
P	8.90	9.10	8.90	9.10	8.90	9.10
P1	5.90	6.10	5.90	6.10	5.90	6.10
P2	11.50 BSC		13.50 BSC		15.50 BSC	
X	.30	.40	.30	.40	.30	.40
e	.50 BSC		.50 BSC		.50 BSC	
N	48		56		64	

TOLERANCES UNLESS SPECIFIED		2975 Steiner Way	
DECIMAL	ANGULAR	San Jose, CA 95054	Phone: (408) 727-6116
XXX.X	±	www.IDT.com	Fax: (408) 492-8674
APPROVALS	DATE	TITLE: P4/P4G PACKAGE OUTLINE	
DRAWN		6.10 mm BODY WIDTH TSSOP	
CHECKED		.50 mm PITCH	
SIZE	DRAWING No.	PSC-4039	REV
C			06
DO NOT SCALE DRAWING		SHEET 2	OF 2

Ordering Information

Part / Order Number	Shipping Packaging	Package	Temperature
954206BGLF	Tubes	56-pin TSSOP	0 to +70° C
954206BGLFT	Tape and Reel	56-pin TSSOP	0 to +70° C

"LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

"C" is the device revision designator (will not correlate with the datasheet revision).

Revision History

Rev.	Issue Date	Description	Page #
A	2/22/2016	<ol style="list-style-type: none"> 1. Updated Output Features 2. Updated Electrical tables 3. Reformatted datasheet to latest template. 4. Updated POD drawings. 	Various



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- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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